MBD701, MMBD701L, SMMBD701L

Preferred Device

Silicon Hot-Carrier Diodes

Schottky Barrier Diodes

These devices are designed primarily for high–efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low–cost, high–volume consumer and industrial/commercial requirements. They are also available in a Surface Mount package.

Features

- Extremely Low Minority Carrier Lifetime 15 ps (Typ)
- Very Low Capacitance 1.0 pF @ V_R = 20 V
- High Reverse Voltage to 70 V
- Low Reverse Leakage 200 nA (Max)
- AEC Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit		
Reverse Voltage	V _R	70	V		
Forward Power Dissipation @ T _A = 25°C MBD701 MMBD701L, SMMBD701L Derate above 25°C MBD701 MMBD701L, SMMBD701L	P _F	280 200 2.8 2.0	mW mW/°C		
Operating Junction Temperature Range	TJ	-55 to +125	°C		
Storage Temperature Range	T _{stg}	–55 to +150	°C		

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



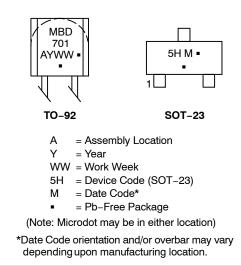
ON Semiconductor®

http://onsemi.com



2 0	- ◀0 1	3 0	▲ −0 1
CATHODE	ANODE	CATHODE	ANODE

MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBD701, MMBD701L, SMMBD701L

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

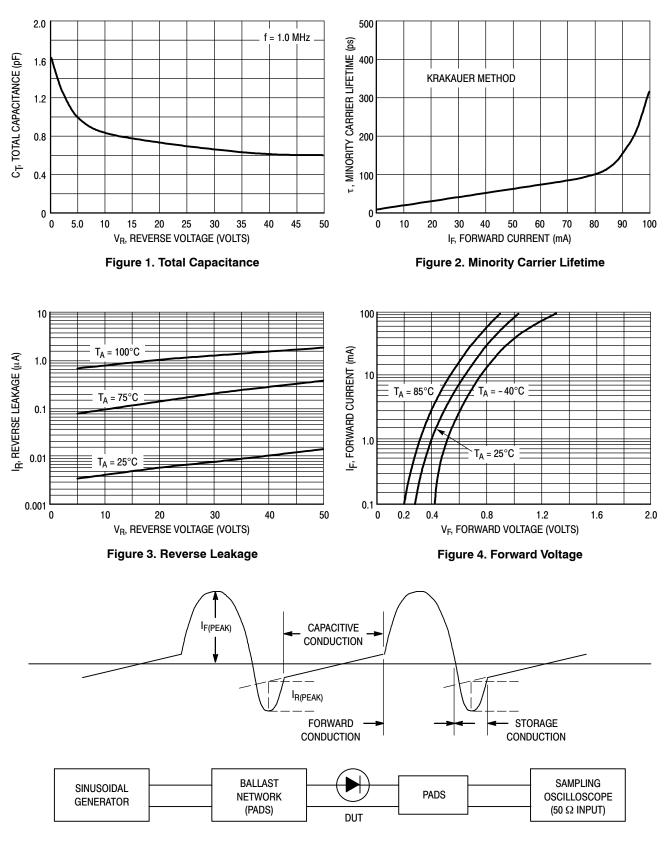
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μAdc)	V _{(BR)R}	70	-	_	V
Total Capacitance (V _R = 20 V, f = 1.0 MHz) Figure 1	CT	-	0.5	1.0	pF
Reverse Leakage (V _R = 35 V) Figure 3	I _R	-	9.0	200	nAdc
Forward Voltage (I _F = 1.0 mAdc) Figure 4	V _F	-	0.42	0.5	Vdc
Forward Voltage (I _F = 10 mAdc) Figure 4	V _F	-	0.7	1.0	Vdc

ORDERING INFORMATION

Device	Package	Shipping [†]
MBD701	TO-92	1,000 Units / Bulk
MBD701G	TO-92 (Pb-Free)	1,000 Units / Bulk
MMBD701LT1	SOT-23	3,000 / Tape & Reel
MMBD701LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBD701LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD701LT3	SOT-23	10,000 / Tape & Reel
MMBD701LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBD701, MMBD701L, SMMBD701L

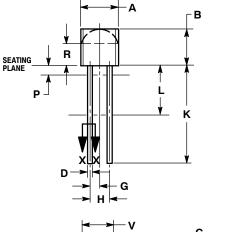


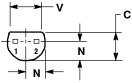
TYPICAL ELECTRICAL CHARACTERISTICS



PACKAGE DIMENSIONS

TO-92 (TO-226AC) CASE 182-06 ISSUE L







SECTION X-X

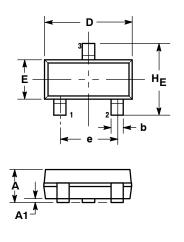
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND ZONE R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

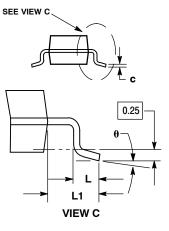
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.21
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.050 BSC		1.27 BSC	
Η	0.100 BSC		2.54 BSC	
ſ	0.014	0.016	0.36 0.4	
Κ	0.500		12.70	
L	0.250		6.35	
Ν	0.080	0.105	2.03	2.66
Ρ		0.050		1.27
R	0.115		2.93	
٧	0.135		3.43	

STYLE 1: PIN 1. ANODE 2. CATHODE

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH
- CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

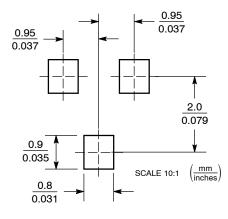
	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
с	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 8:

PIN 1. ANODE 2. NO CONNECTION

3. CATHODE

SOLDERING FOOTPRINT



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